

Title (en)

Use of CMP dispersions for chemo-mechanical polishing of microelectronic parts

Title (de)

Verwendung einer CMP-Dispersion für das chemisch-mechanische Polieren mikroelektronischer Bauteile

Title (fr)

Utilisation d'une dispersion CMP pour le polissage des elements microelectrique

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2005102932A1] The invention relates to a composition in the form of a dispersion or a slurry for chemo-mechanical polishing (CMP) in the production of electronic or micro-electronic components, in particular, semiconductor elements and/or a mechanical component, in particular, a micro-electronic mechanical component or semiconductor element (MEMS), whereby a material is provided with a high ablation rate with a gentle polishing action. The above is achieved, whereby the composition contains titanium oxide particles with approximate formula $TiO_2 \cdot xH_2O \cdot yH_2SO_4$, where the H_2O content of the titanium oxide hydrate particles is 4 - 25 wt. %, preferably 2 - 10 wt. %, and the H_2SO_4 content is 0 - 15 wt. %, preferably 0.1 - 10 wt. %.

IPC 8 full level

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